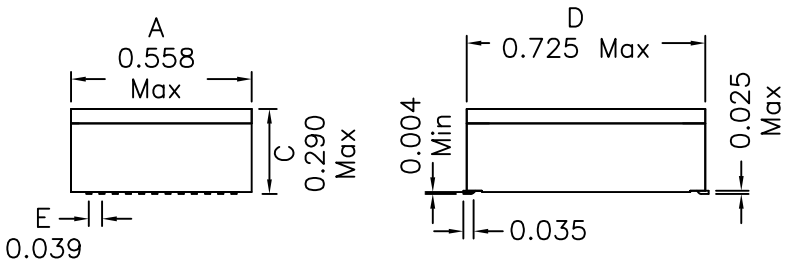
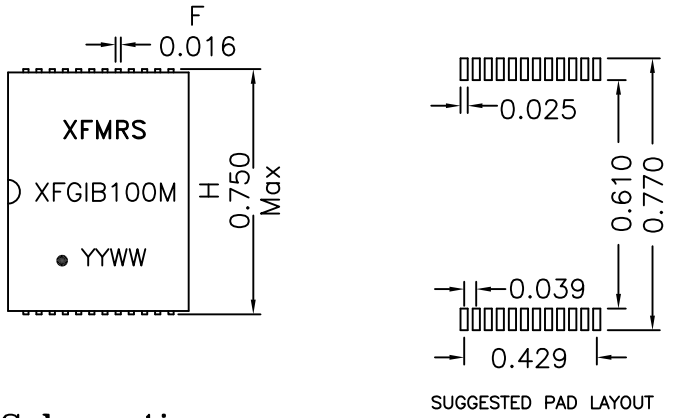
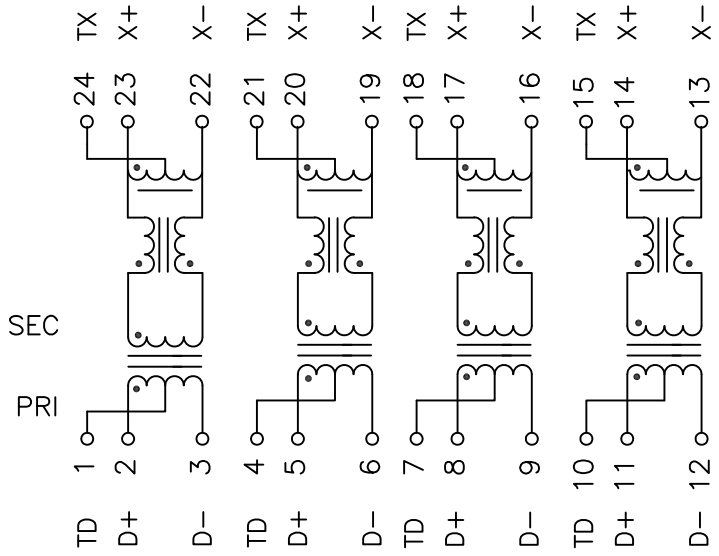
1. Mechanical Dimensions:





SUGGESTED PAD LAYOUT

2. Schematic:



DOC. REV: B/1

3. Electrical Specifications: @25°C

ISOLATION: 1500 Vrms

TURNS RATIO: (PRI/SEC) 1CT:1CT ±2%

OCL: 350uH MIN @100KHz 100mV 8mADC

Q: 5 Min @10KHz 50mV

Rise Time: 1.75ns Max.

INSERTION LOSS: −1.0dB MAX @1MHz−100MHz
−1.5dB MAX @100−125MHz

RETURN LOSS: −18dB Min @1−30MHz
−18dB Min @40MHz −16dB Min @50MHz
−12dB Min @60−80MHz −10dB Min @100MHz

Differential to Common Mode Rejection:
−43dB Min @30MHz −37dB Min @80MHz
−33dB Min @100MHz

CMRR: −30dB Min @1−100MHz

Crosstalk: −45dB Min @30MHz
−40dB Min @60MHz −35dB Min @100MHz

Notes:

1. Solderability: Leads shall meet MIL−STD−202G, Method 208H for solderability.
2. Flammability: UL94V−0
3. ASTM oxygen index: > 28%
4. Insulation System: Class F 155°C. UL file E151556
5. Operating Temperature Range: All listed parameters are to be within tolerance from −40°C to +85°C
6. Storage Temperature Range: −55°C to +125°C
7. Aqueous wash compatible
8. SMD Lead Coplanarity: ±0.004"(0.102mm)
9. Electrical and mechanical specifications 100% tested
10. RoHS Compliant Component

XFMRS Inc www.XFMRS.com	Title: 1000BASE−T Modules		
UNLESS OTHERWISE SPECIFIED TOLERANCES: .xxx ±0.010 Dimensions in INCH	P/N: XFGIB100M		REV. B
	DWN.	Yuan	Oct−30−12
	CHK.	YK Liao	Oct−30−12
SHT 1 OF 1	APP.	BSJ	Oct−30−12

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